

# SN54LV244, SN74LV244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCLS194C – FEBRUARY 1993 – REVISED APRIL 1996

- **EPIC™ (Enhanced-Performance Implanted CMOS) 2- $\mu$  Process**
- **Typical  $V_{OLP}$  (Output Ground Bounce) < 0.8 V at  $V_{CC}$ ,  $T_A = 25^\circ\text{C}$**
- **Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) > 2 V at  $V_{CC}$ ,  $T_A = 25^\circ\text{C}$**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs**

## description

These octal buffers/line drivers are designed for 2.7-V to 5.5-V  $V_{CC}$  operation.

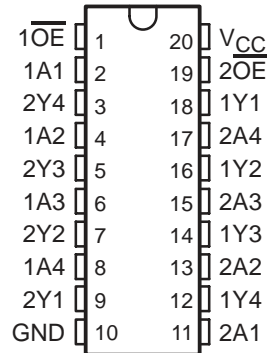
The 'LV244 are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'LV244 are organized as two 4-bit line drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

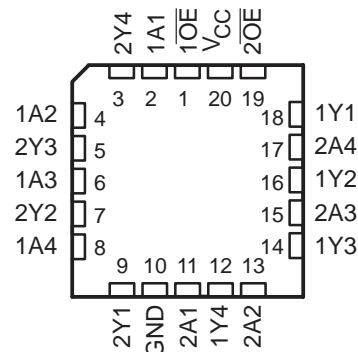
The SN74LV244 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV244 is characterized for operation over the full military temperature range of  $-55^\circ\text{C}$  to  $125^\circ\text{C}$ . The SN74LV244 is characterized for operation from  $-40^\circ\text{C}$  to  $85^\circ\text{C}$ .

SN54LV244 . . . J OR W PACKAGE  
SN74LV244 . . . DB, DW, OR PW PACKAGE  
(TOP VIEW)



SN54LV244 . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z



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**TEXAS  
INSTRUMENTS**

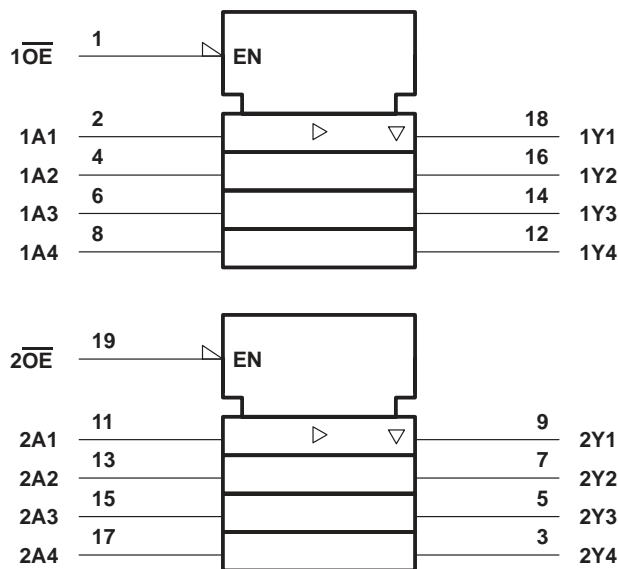
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# SN54LV244, SN74LV244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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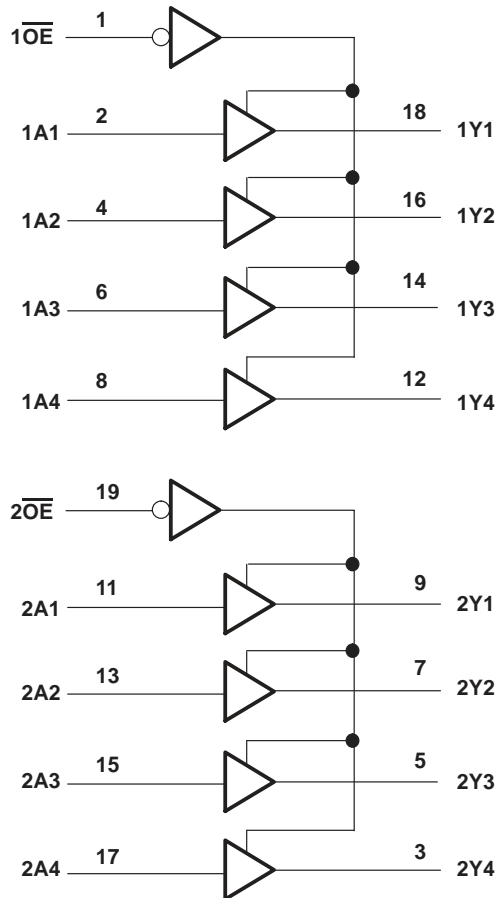
## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for DB, DW, J, PW, and W packages.

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Notes 1 and 2) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 50$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 70$ mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3):	
DB package .....	0.6 W
DW package .....	1.6 W
PW package .....	0.7 W
Storage temperature range, $T_{stg}$ .....	$-65^\circ\text{C}$ to $150^\circ\text{C}$

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. This value is limited to 7 V maximum.  
 3. The maximum package power dissipation is calculated using a junction temperature of  $150^\circ\text{C}$  and a board trace length of 750 mils.



# SN54LV244, SN74LV244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 4)

		SN54LV244		SN74LV244		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	2.7	5.5	2.7	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		2		V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		3.15		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		0.8		V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		1.65		
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		-8		mA
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		-16		
$I_{OL}$	Low-level output current	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		8		mA
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		16		
$\Delta t/\Delta v$	Input transition rise or fall rate	0	100	0	100	ns/V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}^\dagger$	SN54LV244			SN74LV244			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$V_{OH}$	$I_{OH} = -100\ \mu\text{A}$	MIN to MAX	$V_{CC} - 0.2$			$V_{CC} - 0.2$			V
	$I_{OH} = -8\ \text{mA}$	3 V	2.4			2.4			
	$I_{OH} = -16\ \text{mA}$	4.5 V	3.6			3.6			
$V_{OL}$	$I_{OL} = 100\ \mu\text{A}$	MIN to MAX	0.2			0.2			V
	$I_{OL} = 8\ \text{mA}$	3 V	0.4			0.4			
	$I_{OL} = 16\ \text{mA}$	4.5 V	0.55			0.55			
$I_I$	$V_I = V_{CC}$ or GND	3.6 V	$\pm 1$			$\pm 1$			$\mu\text{A}$
		5.5 V	$\pm 1$			$\pm 1$			
$I_{OZ}$	$V_O = V_{CC}$ or GND	3.6 V	$\pm 5$			$\pm 5$			$\mu\text{A}$
		5.5 V	$\pm 5$			$\pm 5$			
$I_{CC}$	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	20			20			$\mu\text{A}$
		5.5 V	20			20			
$\Delta I_{CC}$	One input at $V_{CC} - 0.6\text{ V}$ , Other inputs at $V_{CC}$ or GND	3 V to 3.6 V	500			500			$\mu\text{A}$
$C_i$	$V_I = V_{CC}$ or GND	3.3 V	3			3			pF
		5 V	3			3			
$C_o$	$V_O = V_{CC}$ or GND	3.3 V	8			8			pF
		5 V	8			8			

$^\dagger$  For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

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# SN54LV244, SN74LV244 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LV244						UNIT		
			$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$			$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$				$V_{CC} = 2.7 \text{ V}$	
			MIN	TYP	MAX	MIN	TYP	MAX		MIN	MAX
$t_{pd}$	A	Y		7	12		9	14		17	ns
$t_{en}$	$\overline{OE}$	Y		10	19		13	23		29	ns
$t_{dis}$	$\overline{OE}$	Y		10	20		13	21		24	ns

switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74LV244						UNIT		
			$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$			$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$				$V_{CC} = 2.7 \text{ V}$	
			MIN	TYP	MAX	MIN	TYP	MAX		MIN	MAX
$t_{pd}$	A	Y		7	12		9	14		17	ns
$t_{en}$	$\overline{OE}$	Y		10	19		13	23		29	ns
$t_{dis}$	$\overline{OE}$	Y		10	20		13	21		24	ns

operating characteristics,  $T_A = 25^\circ\text{C}$

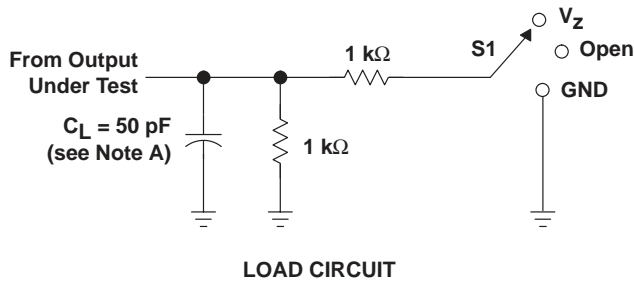
PARAMETER		TEST CONDITIONS		$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance per buffer/driver	Outputs enabled	$C_L = 50 \text{ pF}, \quad f = 10 \text{ MHz}$	3.3 V	40	pF
		Outputs disabled			4	
		Outputs enabled		5 V	73	
		Outputs disabled			4	

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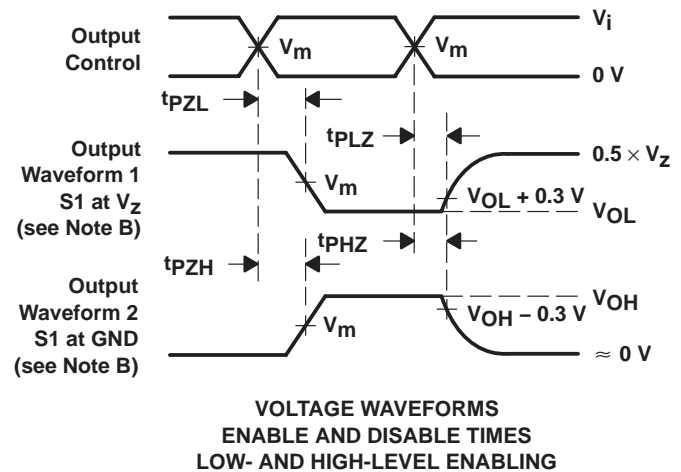
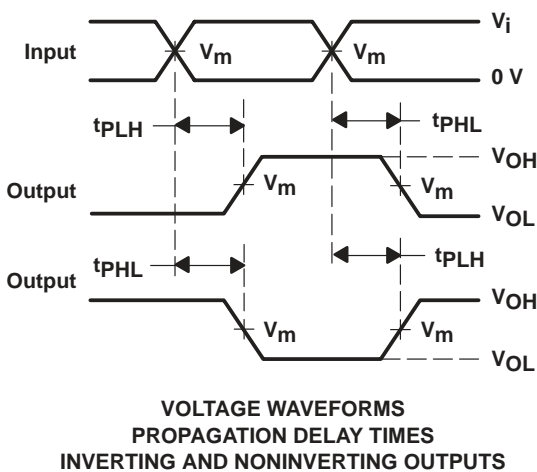
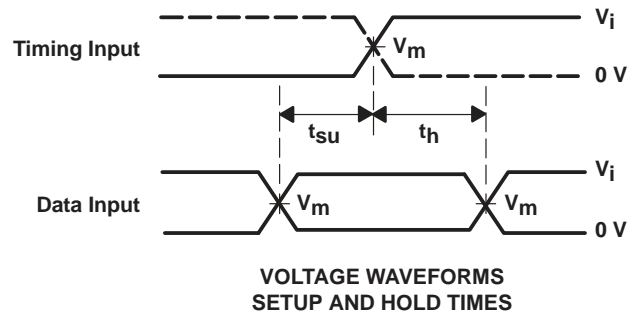
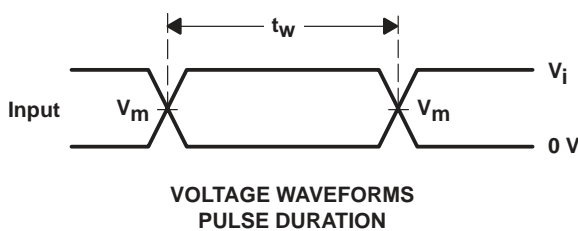
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PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>Z</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

WAVEFORM CONDITION	V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> = 2.7 V to 3.6 V
V <sub>m</sub>	0.5 × V <sub>CC</sub>	1.5 V
V <sub>i</sub>	V <sub>CC</sub>	2.7 V
V <sub>Z</sub>	2 × V <sub>CC</sub>	6 V



- NOTES:
- A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns, t<sub>f</sub> ≤ 2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LV244DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	-40 to 85		
SN74LV244DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
SN74LV244DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
SN74LV244PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

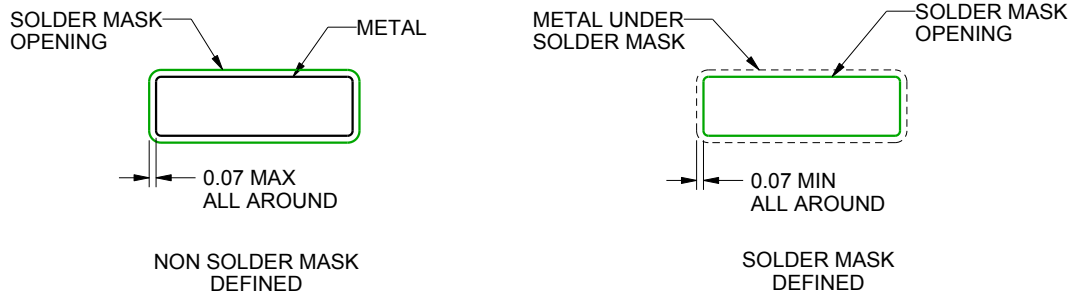
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

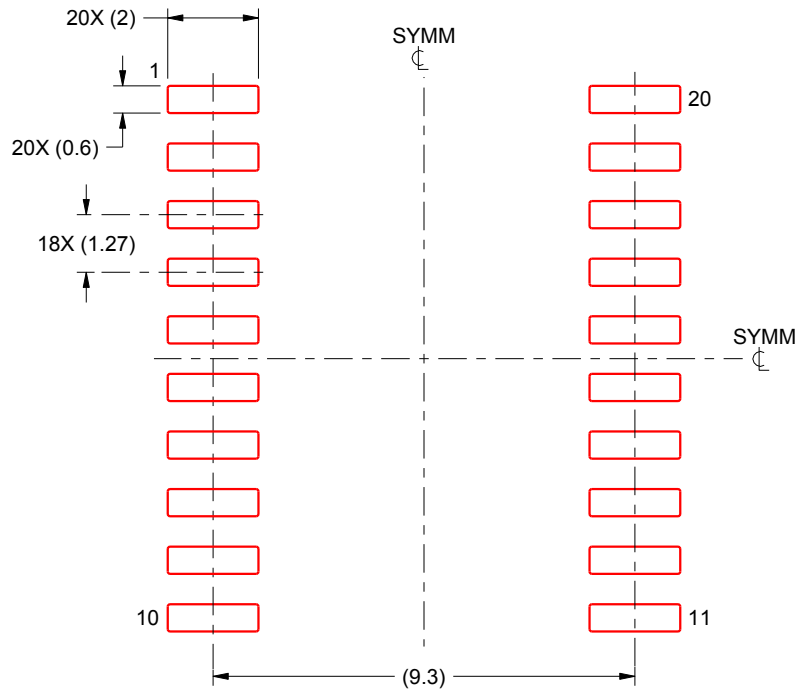


# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

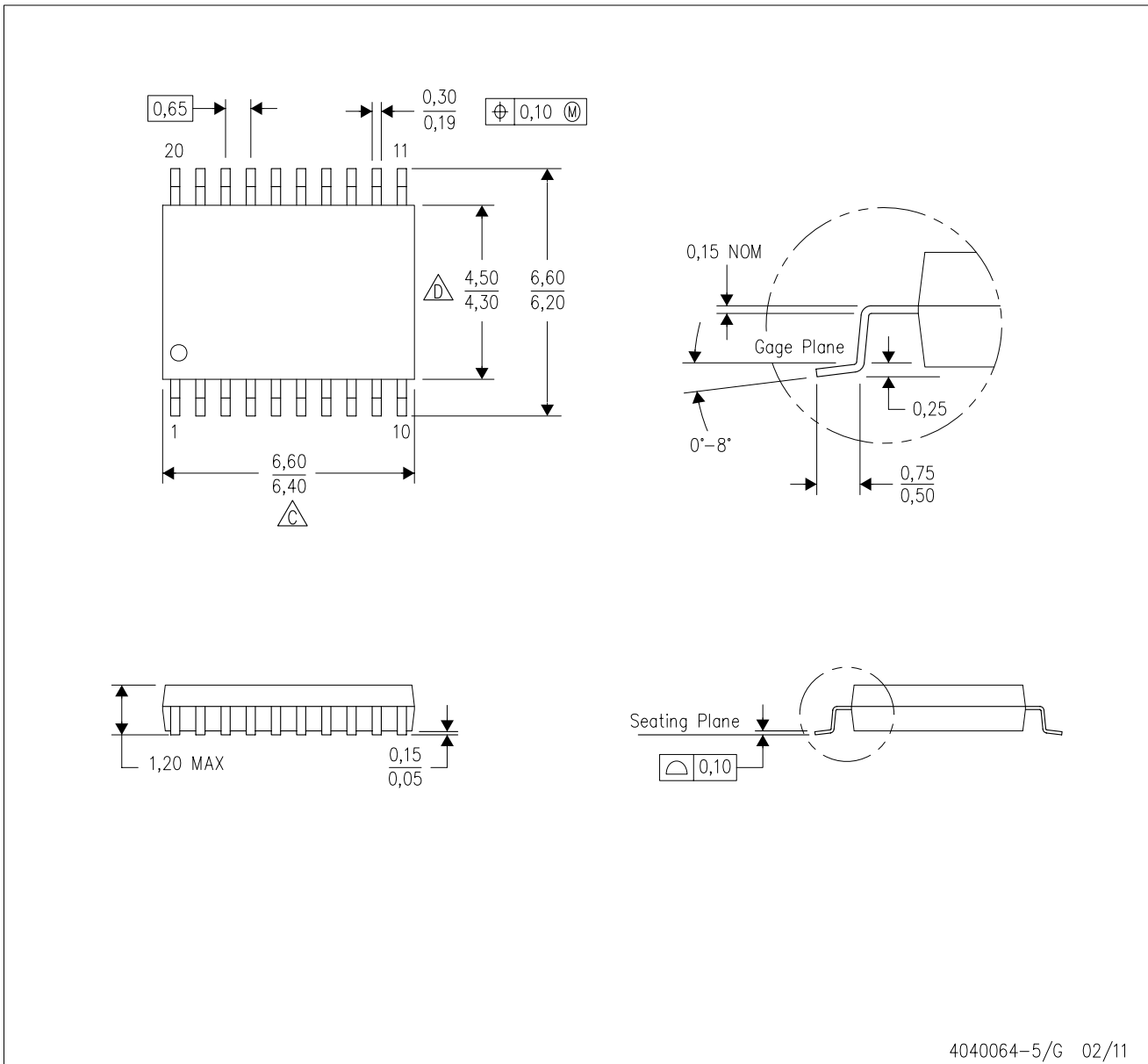
4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



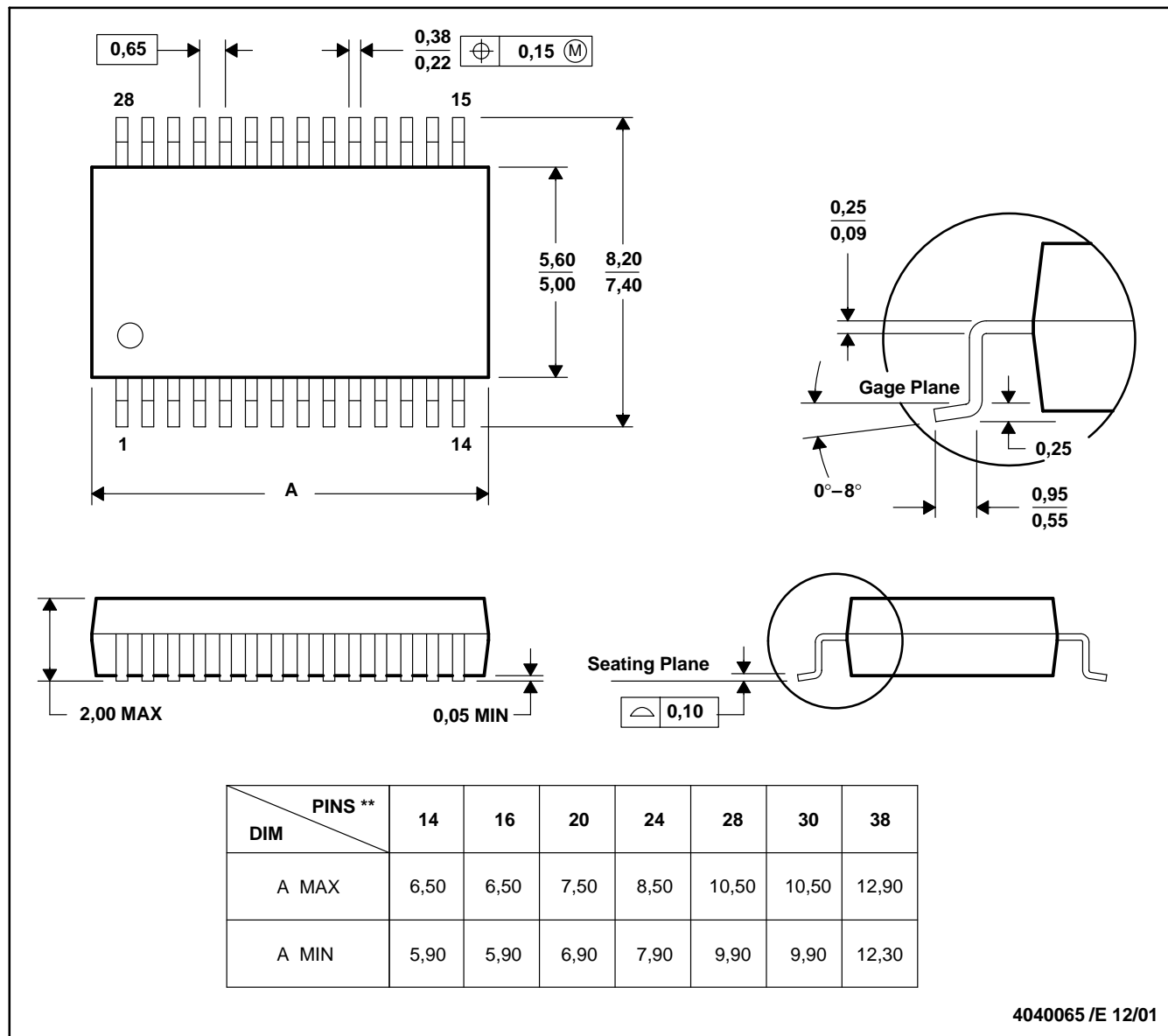
4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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### Applications

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Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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